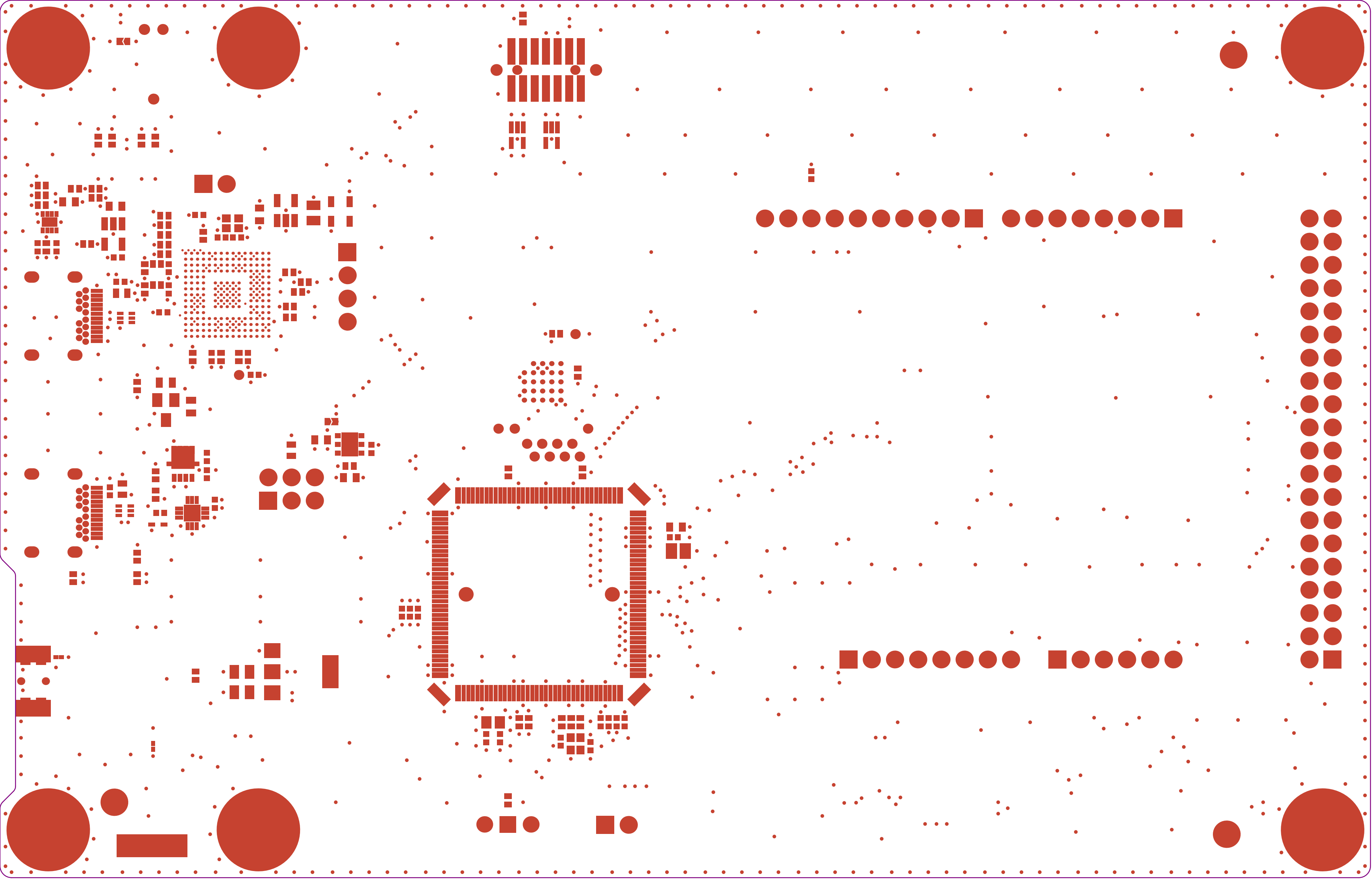
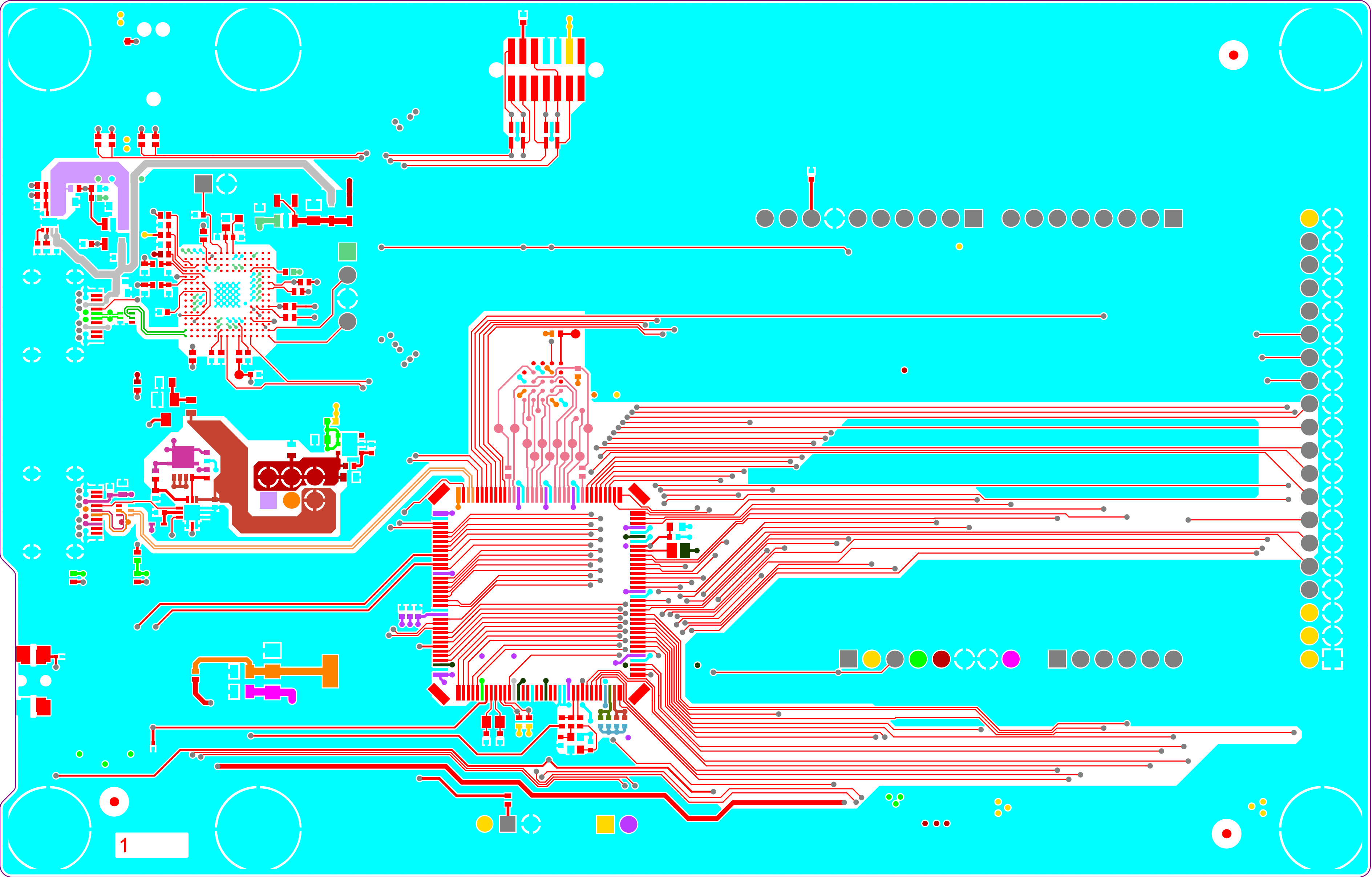


Top Overlay

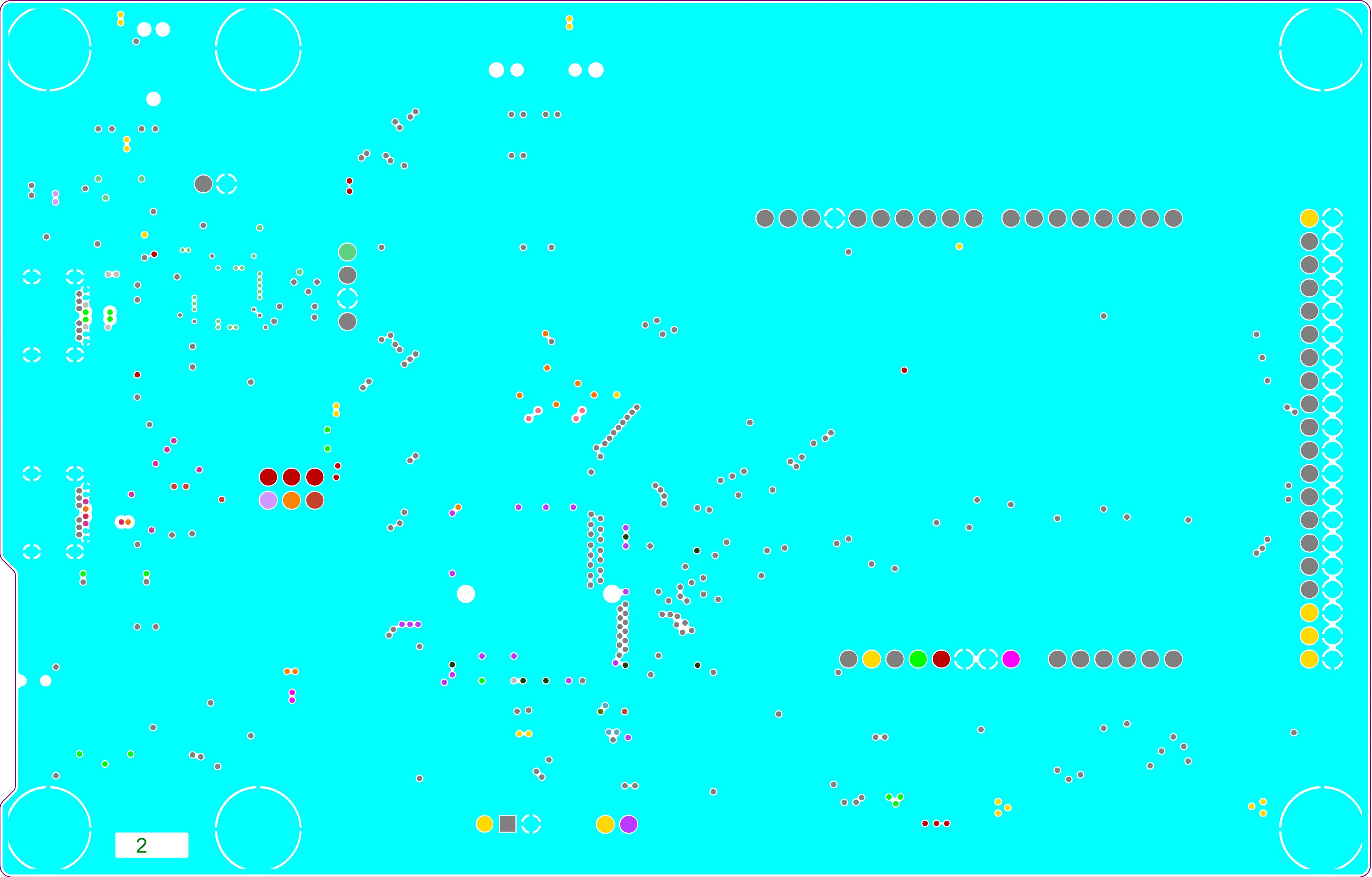
.GTO

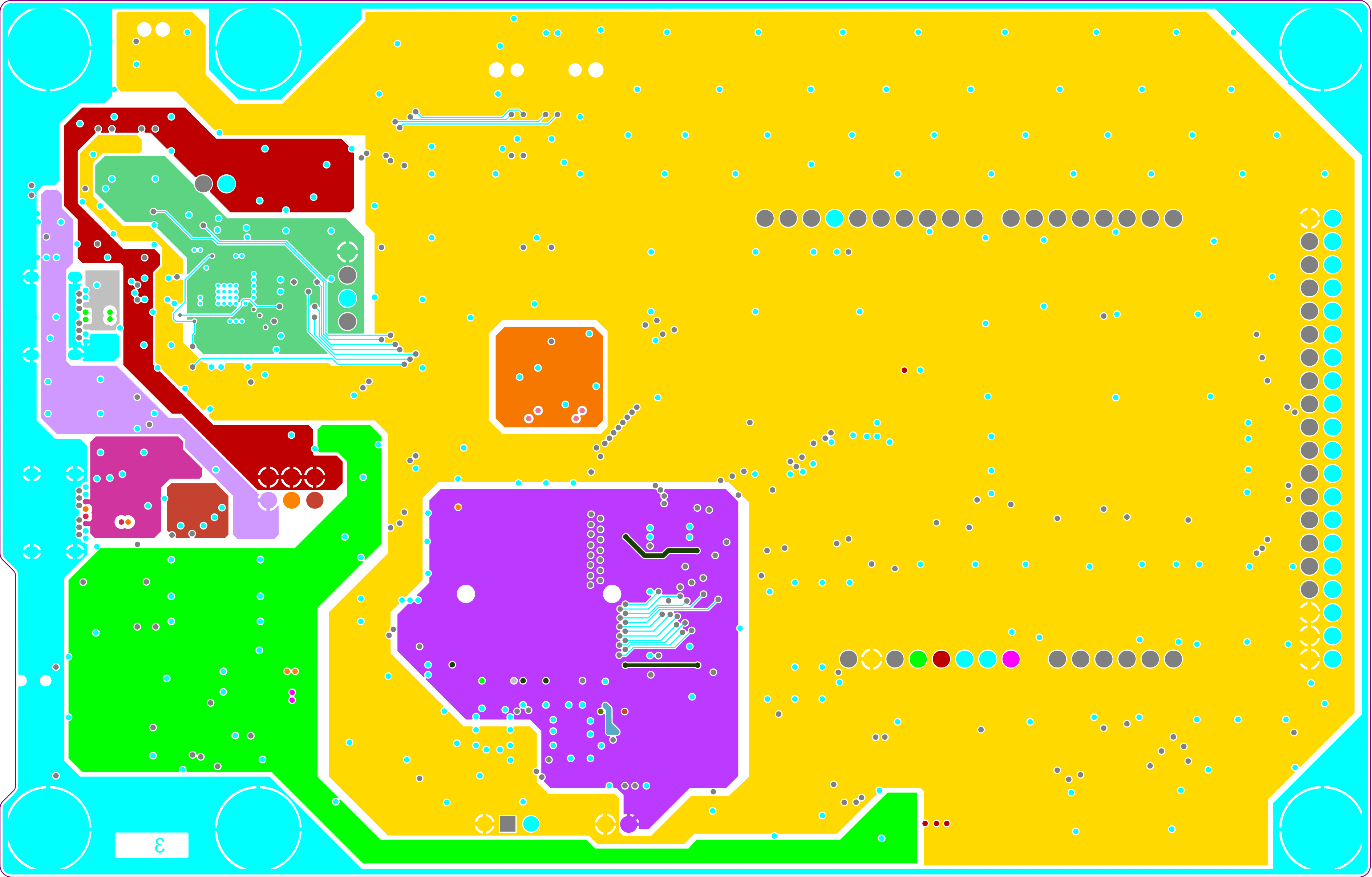


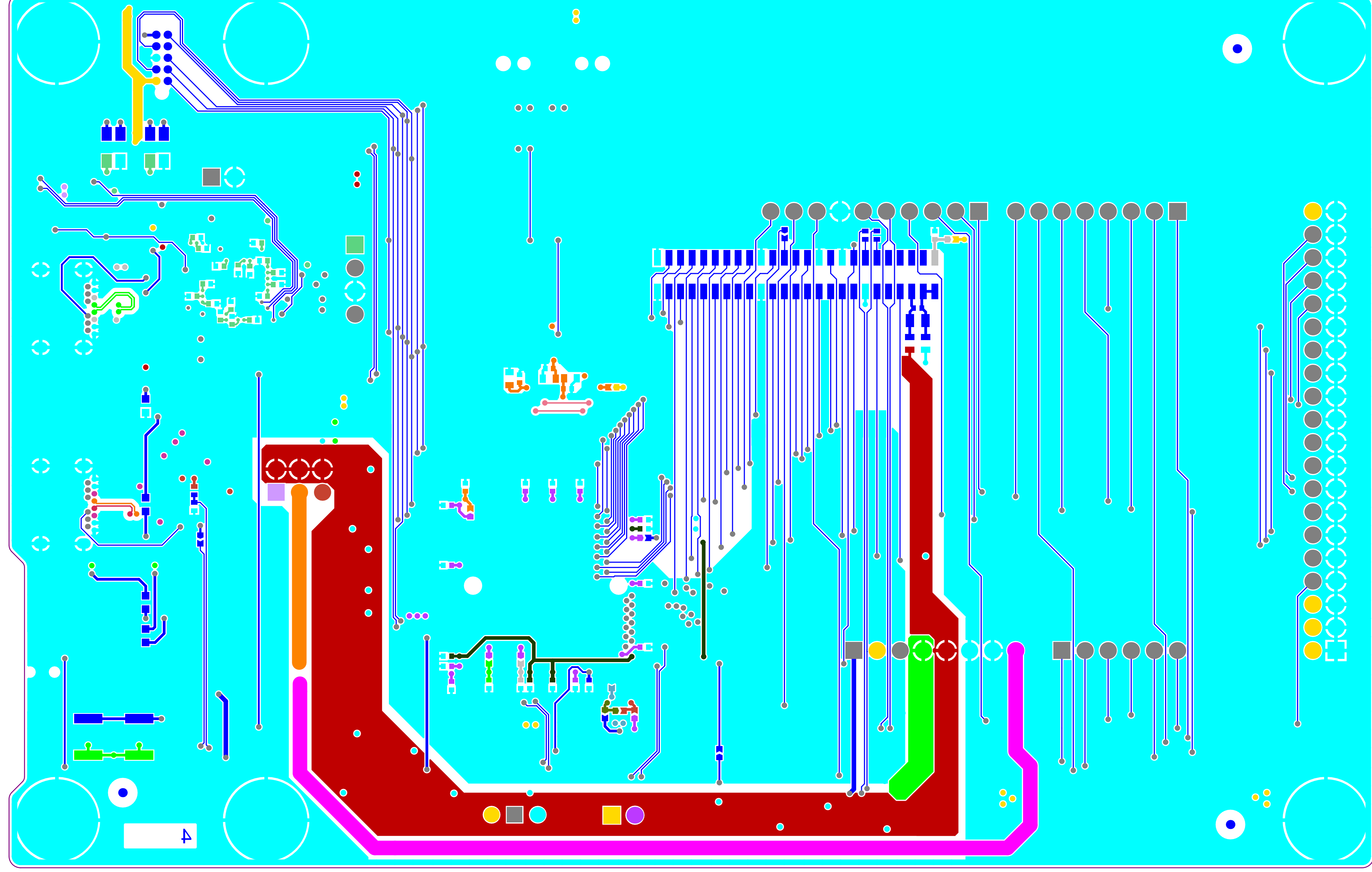


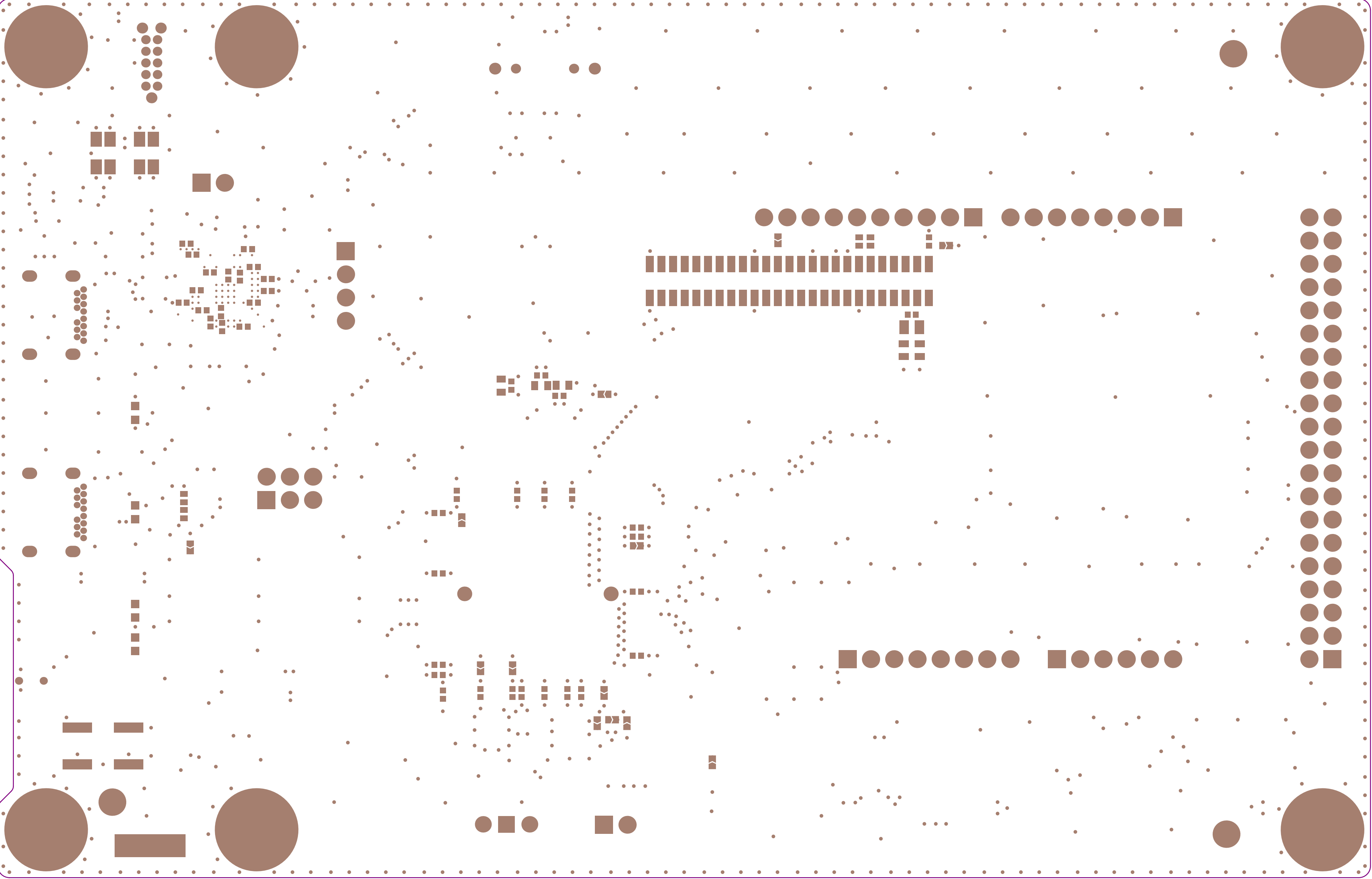
Top Layer

.GTL









.GBS

Bottom Solder



PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

N/A

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK

☒ WHITE

☐ YELLOW

☐ BLACK

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ NO

☒ YES (SEE XLS FILE FOR DETAIL INFORMATION)

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK

☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

MINIMUM PARAMETERS

DEFAULT

TRACKS : 0.12mm

GAPS : 0.12mm

PCB : TYPE 3

ASPECT-RATIO, AXE Z :

DEFAULT

< 6:1















LEVEL "A"

STLink

> 8 : 1

LEVEL "C"

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.015mm	3.5	
1	Top Layer		0.035mm		
	Dielectric 1	FR4	0.106mm	4.2	
2	Signal Layer 1		0.017mm		
	Dielectric 2	FR4	1.200mm	4.5	
3	Signal Layer 2		0.017mm		
	Dielectric 3	FR4	0.106mm	4.2	
4	Bottom Layer		0.035mm		
	Bottom Solder	Solder Resist	0.015mm	3.5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
	2	0.450mm (17.72mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded
	2	0.750mm (29.53mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	2	0.970mm (38.19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	2	1.190mm (46.85mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	2	1.500mm (59.06mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	3	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
	3	1.100mm (43.31mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	6	0.450mm (17.72mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded
	6	4.500mm (177.17mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	28	0.400mm (15.75mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	32	1.100mm (43.31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	54	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	56	0.150mm (5.91mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	917	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	1115 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout